

General Description

BD2564CN is a Bluetooth 5.1 BR/EDR & LE dual mode transceiver module.

The module integrates Bluetooth classic and Bluetooth Low Energy radio TI's CC2564C, a 26-MHz crystal oscillator, a band pass filter and all the passive components at a very affordable cost.

The module provides the best-in-class RF performance with transmit power and receive sensitivity that provides twice the range and higher throughput than other Bluetooth-low-energy-only solutions. The power-management hardware and software algorithms provide significant power savings in all commonly used Bluetooth BR/EDR and low energy modes of operation.

The certified and royalty free Dual-mode Bluetooth 4.2 protocol stack software provides a complete Bluetooth BR/EDR, and Bluetooth Low Energy sample applications that reduce design effort and ensure a faster time to market.

The module has a very small form factor with the dimensions of 7 mm x 7 mm x 1.55 mm.



Key Features

- Bluetooth 5.1 dual mode
 - Bluetooth Basic Rate (BR)
 - Enhanced Data Rate (EDR)
 - Low Energy (LE)
- BR and EDR features include:
 - Up to seven active devices
 - Scatternet: Up to three piconets simultaneously, one as master and two as slaves
 - Up to two Synchronous Connection Oriented (SCO) links on the same piconet
 - Support for all voice air-coding – continuously Variable Slope Delta (CVSD), A-Law, μ -Law, modified Subband Coding (mSBC), and transparent (Uncoded)
 - Provide an assisted mode for HFP 1.6 Wideband Speech (WBS) profile or A2DP profile to reduce host processing and power
 - Support of multiple Bluetooth profiles with enhanced QoS
- Low Energy features include:
 - Multiple sniff instances tightly coupled to achieve minimum power consumption
 - Independent buffering for Low Energy allows large numbers of multiple connections without affecting BR or EDR performance
- Best-in-Class Bluetooth (RF) performance (TX power, RX sensitivity, blocking)
 - Built-In coexistence and prioritization handling for BR, EDR, and Low Energy
 - Capabilities of link layer topology, Scatternet - can act concurrently as peripheral and central
 - Network support for up to 10 devices
 - Time line optimization algorithms to achieve maximum channel utilization
- Advanced power management for extended battery life and ease of design
 - Class 1 TX power up to +12 dBm
 - Internal temperature detection and compensation to ensure minimal variation in RF performance over temperature, no external calibration required
 - Improved Adaptive Frequency Hopping (AFH)
 - Algorithm with minimum adaptation time
 - Longer range, including twice the range of other Low-Energy-Only solutions
 - On-Chip power management, including direct connection to battery
 - Low power consumption for active, standby,

- and scan Bluetooth modes
- Shutdown and sleep modes to minimize power consumption
- Physical interfaces:
 - UART Interface with support for maximum Bluetooth data rates
 - UART transport layer (H4) with maximum rate of 4 Mbps
 - Three-Wire UART transport layer (H5) with maximum rate of 4 Mbps
 - Fully programmable Digital Pulse-Code Modulation (PCM) - I2S codec interface
- Flexibility for easy stack integration and validation
 - into MCUs and MPUs
- HCI tester tool to evaluate RF performance of the device and configure service pack
- Antenna: without antenna
- Size: 7 mm x 7 mm x 1.55 mm (With Shield)
- Standards Conformance
 - *Bluetooth*® SIG
 - CE-RED (Europe)
 - FCC (US)
 - ISED (Canada)
 - Japan (Telec)

Applications

- Mobile Accessories
- Sports and Fitness Applications
- Wireless Audio Solutions
- Set-Top Boxes and Remote Controls
- Toys
- Test and Measurement
- Industrial: Cable Replacement
- Wireless Sensors
- Automotive Aftermarket
- Wellness and Health

Contents

General Description	1
Key Features.....	1
Applications	3
Contents.....	4
1. Block Diagram.....	5
2. Pinout	6
3. Characteristics	7
3.1. Absolute Maximum Ratings	7
3.2. Recommended Operating Conditions	8
4. Mechanical Specifications	9
4.1. Dimensions	9
4.2. PCB Footprint	10
5. Marking	10
6. Ordering Information	11
7. Regulation.....	11
7.1. FCC Warning.....	11
7.2. FCC Statements	12
7.3. Module statement	12
7.4. IC Statements	13
8. Revision History	14
Contacts	14

1. Block Diagram

BD2564CN integrates Bluetooth classic and Bluetooth Low Energy radio TI's CC2564C, a 26-MHz crystal oscillator, a band pass filter and all the passive components at a very affordable cost.

Figure 1-1 shows the block diagram of the module.



Figure 1-1. The block diagram of BD2564CN (Confidential)

2. Pinout

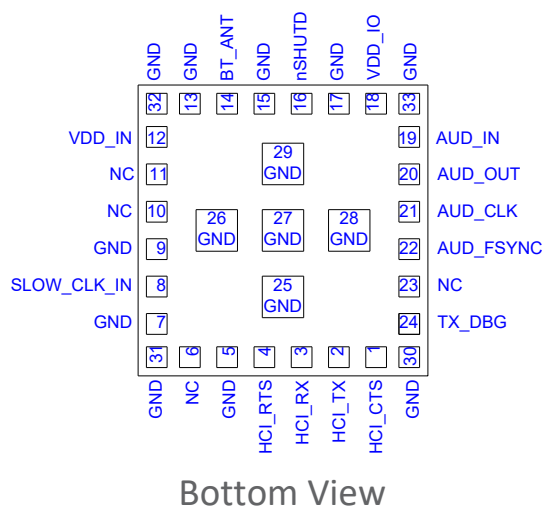


Figure 2-1. Pinout Diagram Top View

Table 2-1 describes the definitions of the pins.

Table 2-1. Pin Description

Pin #	Pin Name	Type	Description
1	HCI_CTS	DI ^(Note 1) , PU ^(Note 2)	HCI UART clear-to-send. The device can send data when HCI_CTS is low
2	HCI_TX	DO, PU	HCI UART data transmit
3	HCI_RX	DI, PU	HCI UART data receive
4	HCI_RTS	DO, PU	HCI UART request-to-send. Host can send data when HCI_RTS is low
5	GND	GND	Power ground
6	NC	-	Not connected
7	GND	DIO	GPIO, Sensor Controller
8	SLOW_CLK_IN	DI	32.768-kHz clock in, fail-safe
9	GND	GND	Power ground
10	NC	-	Not connected
11	NC	-	Not connected
12	VDD_IN	Power	Main power supply for the module (2.2 to 4.8 V)
13	GND	GND	Power ground
14	BT_ANT	AIO	Bluetooth RF I/O
15	GND	GND	Power ground
16	nSHUTD	DI, PD	Shutdown input (active low)
17	GND	GND	Power ground
18	VDD_IO	Power	I/O power supply (1.8 V nominal)
19	AUD_IN	DI, PD	PCM data input, fail-safe
20	AUD_OUT	DO, PD	PCM data onput, fail-safe
21	AUD_CLK	DIO ^(Note 1) , PD	PCM clock, fail-safe

Pin #	Pin Name	Type	Description
22	AUD_FSYNC	DIO, PD	PCM frame sync, fail-safe
23	NC	-	Not connected
24	TX_DBG	DO, PU	Internal debug messages
25	GND	GND	Power ground
26	GND	GND	Power ground
27	GND	GND	Power ground
28	GND	GND	Power ground
29	GND	GND	Power ground
30	GND	GND	Power ground
31	GND	GND	Power ground
32	GND	GND	Power ground
33	GND	GND	Power ground

Note 1: DI stands for Digital Input, DO stands for Digital Output, DIO stands for Digital Input-Output, AIO stands for Analog Input Output;

Note 2: PU stands for internal Pull-Up, PD stands for internal Pull-Down.

3. Characteristics

All MIN/MAX specification limits are guaranteed by design, production testing and/or statistical characterization. Typical values are based on characterization results at default measurement conditions and are informative only.

Default measurement conditions (unless otherwise specified): VDD_IN = 3.6 V, VDD_IO = 1.8V, TA = 25 °C. All radio measurements are performed with standard RF measurement equipment.

3.1. Absolute Maximum Ratings

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Table 3-1. Absolute Maximum Ratings

PARAMETER	MIN	MAX	UNIT	Notes
VDD_IN	-0.5	4.8	V	
VDD_IO	-0.5	2.415	V	
Input voltage to analog pin	-0.5	2.1	V	BT_ANT
Input voltage to all other pins	-0.5	VDD_IO + 0.5		
Bluetooth RF pin		8	dBm	
Storage Temperature	-40	100	°C	

3.2. Recommended Operating Conditions

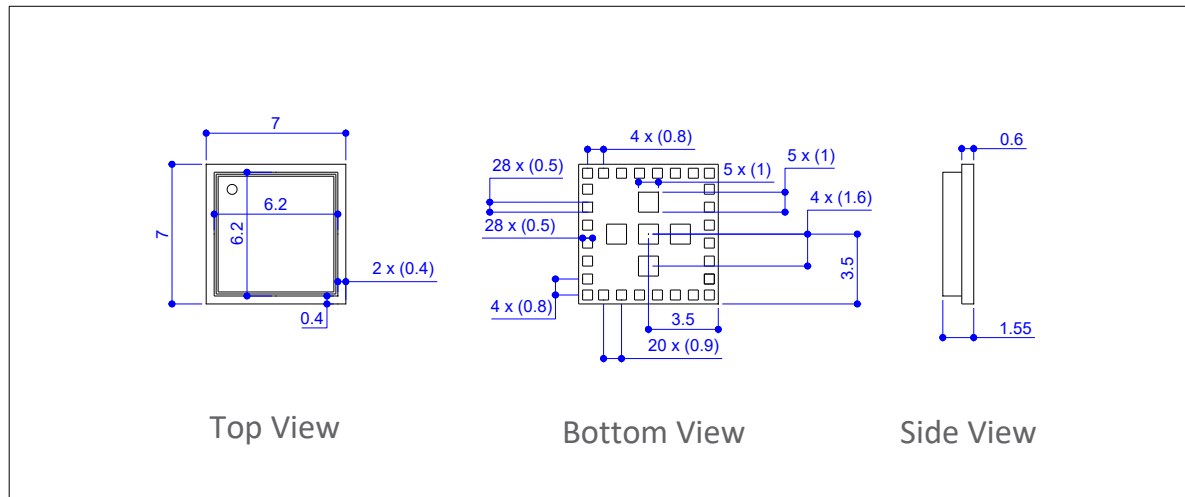
Table 3-2. Recommended Operating Conditions

PARAMETER	MIN	TYP	MAX	UNIT
VDD_IN	2.2		4.8	V
VDD_IO	1.62		1.92	V
Operating Temperature	-40	-	85	°C

4. Mechanical Specifications

4.1. Dimensions

The module dimensions are presented in the following figure:



Note: All dimensions are in millimeter

Figure 4-1. Mechanical Drawing

6. Regulation

7.1. FCC Warning

Integration instructions for host product manufacturers according to KDB 996369 D03 OEM Manual v01

1. List of applicable FCC rules
FCC Part 15.247

2. Specific operational use conditions
This transmitter/module and its antenna(s) must not be co-located or operating in conjunction with any transmitter. This information also extends to the host manufacturer's instruction manual.

3. Limited module procedures
Not applicable

4. Trace antenna designs
It is "not applicable" as trace antenna which is not used on the module.

5. RF exposure considerations
This equipment complies with FCC RF radiation exposure limits set forth for an uncontrolled environment. This compliance to FCC radiation exposure limits for an uncontrolled environment, and minimum of 20cm separation between antenna and body.
The host product manufacturer would provide the above information to end users in their end-product manuals.

6. Antennas
Antenna 1: Chip antenna; 0.5dBi; 2.402 GHz ~ 2.480GHz
Antenna 2: Whip antenna; 2.5dBi; 2.402 GHz ~ 2.480GHz
Antenna 3: Chip antenna; 0.8dBi; 2.402 GHz ~ 2.480GHz

7. Label and compliance information
The end product must carry a physical label or shall use e-labeling followed KDB784748D01 and KDB 784748 stating "Contains Transmitter Module FCC ID: P9R-2564C".

8. Information on test modes and additional testing requirements. For more information on testing, please contact the manufacturer.

9. Additional testing, Part 15 Subpart B disclaimer
The modular transmitter is only FCC authorized for the specific rule parts (FCC Part 15.247) listed on the grant, and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by

the modular transmitter grant of certification. The final host product still requires Part 15 Subpart B compliance testing with the modular transmitter installed when contains digital circuitry.

7.2. FCC Statements

(OEM) Integrator has to assure compliance of the entire end-product incl. the integrated RF Module. For 15 B (§15.107 and if applicable §15.109) compliance, the host manufacturer is required to show compliance with 15 while the module is installed and operating.

Furthermore the module should be transmitting and the evaluation should confirm that the module's intentional emissions (15C) are compliant (fundamental / out-of-band). Finally the integrator has to apply the appropriate equipment authorization (e.g. Verification) for the new host device per definition in §15.101.

Integrator is reminded to assure that these installation instructions will not be made available to the end-user of the final host device.

The final host device, into which this RF Module is integrated" has to be labeled with an auxiliary label stating the FCC ID of the RF Module, such as "Contains FCC ID: P9R-2564C

"This device complies with part 15 of the FCC rules. Operation is subject to the following two conditions:

- (1) this device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation."

"Changes or modifications to this unit not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment."

The Integrator will be responsible to satisfy SAR/ RF Exposure requirements, when the module integrated into the host device.

7.3. Module statement

The single-modular transmitter is a self-contained, physically delineated, component for which compliance can be demonstrated independent of the host operating conditions, and which complies with all eight requirements of § 15.212(a)(1) as summarized below.

- (1) The radio elements have the radio frequency circuitry shielded.
- (2) The module has buffered modulation/data inputs to ensure that the device will comply with Part 15 requirements with any type of input signal.
- (3) The module contains power supply regulation on the module.
- (4) The module contains a permanently attached antenna.
- (5) The module demonstrates compliance in a stand-alone configuration.

- (6) The module is labeled with its permanently affixed FCC ID label.
- (7) The module complies with all specific rules applicable to the transmitter, including all the conditions provided in the integration instructions by the grantee.
- (8) The module complies with RF exposure requirements.

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help

7.4. IC Statements

The final host device, into which this RF Module is integrated" has to be labeled with an auxiliary label stating the IC of the RF Module, such as" Contains transmitter module IC: 324C-2564C

Le périphérique hôte final, dans lequel ce module RF est intégré "doit être étiqueté avec une étiquette auxiliaire indiquant le CI du module RF, tel que" Contient le module émetteur IC: 324C-2564C

This device contains licence-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's licence-exempt RSS(s). Operation is subject to the following two conditions:

- (1) This device may not cause interference.
- (2) This device must accept any interference, including interference that may cause undesired operation of the device.

L'émetteur/récepteur exempt de licence contenu dans le présent appareil est conforme aux CNR d'Innovation, Sciences et Développement économique Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes :

- (1) L'appareil ne doit pas produire de brouillage;
- (2) L'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

RF Exposure Warning Statements:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment.

This equipment shall be installed and operated with minimum distance 20cm between the radiator & body.

Radio Frequency Exposure Statement for IC:

The device has been evaluated to meet general RF exposure requirements. The device can be used in mobile exposure conditions. The min separation distance is 20cm.

Déclaration d'exposition aux radiofréquences pour IC:

L'appareil a été évalué pour répondre aux exigences générales en matière d'exposition aux RF. L'appareil peut être utilisé dans des conditions d'exposition mobiles. La distance de séparation minimale est de 20 cm.

This radio transmitter [IC: 324C-2564C] has been approved by Innovation, Science and Economic Development Canada to operate with the antenna types listed below, with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.

Cet émetteur radio [IC: 324C-2564C] a été approuvé par Innovation, Sciences et Développement économique Canada pour fonctionner avec les types d'antenne énumérés ci-dessous, avec le gain maximal admissible indiqué. Les types d'antenne non inclus dans cette liste qui ont un gain supérieur au gain maximum indiqué pour tout type répertorié sont strictement interdits pour une utilisation avec cet appareil.

7. Revision History

Revision	Date	Description
V1.0	17-July-2021	Initial Release, brief
V1.1	22-November-2021	Update some data, replace picture

Contacts

Guangzhou BDE Technology Inc.

USA: 67 E Madison St, # 1603A, Chicago, IL 60603, US

Tel: +1-312-379-9589

Website: <http://www.bdecomm.com>

Email: info@bdecomm.com

China: B2-403, ChuangYi Building, 162 Science Avenue, Huangpu District, Guangzhou 510663, China

Tel: +86-20-28065335

Website: <http://www.bdecomm.com>

Email: sales@bdecomm.com